



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-11-20
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32C092GCU6	71MB*44DXXXA	A	998Z	2024-11-20
Amount	Unit of measure	Unit type	ST ECOPACK grade	
27	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	4x4	28	Flat	
Comment	Package : A0B0 UFQFPN 4X4X0.55 28L PITCH0.5 COL 8202209			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration :						Mfr Item Name	71MB*44DXXXA		26.6886		5000000.0	1000000.0				
note : Substance present with less 0.001mg will not be declared in this document																
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	4.595	mg	supplier	die	Silicon (Si)	7440-21-3		4.416	mg	961100	165473				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	1945	335				
				supplier	metallization	Copper (Cu)	7440-50-8		0.075	mg	16393	2822				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.024	mg	5279	909				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	278	48				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	278	48				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.019	mg	4169	718				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.049	mg	10558	1818				
				DAF (HR-5104T-25)	Other Organic Materials	0.550	mg	supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.052	mg	95238	1961
								supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.079	mg	142857	2942
supplier	Organic Compounds	Phenol Resin	Proprietary						0.079	mg	142857	2942				
supplier	Organic Compounds	SiO2 Filler	Proprietary						0.262	mg	476190	9806				
supplier	Metals	(Meta)Acrylic Copolymer	Proprietary						0.079	mg	142857	2942				
supplier	Organic Compounds	Epoxy Resin	Proprietary						0.198	mg	21000	7411				
Encapsulation (EME-G770HCD-MD)	Other Organic Materials	9.418	mg	supplier	Organic Compounds	Phenol Resin	Proprietary		0.198	mg	21000	7411				
				supplier	Glass	Silica(Amorphous)A	60676-86-0		7.878	mg	836450	295174				
				supplier	Glass	Silica(Amorphous)B	7631-86-9		1.086	mg	115320	40695				
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.059	mg	6230	2198				
				supplier	Metals	Gold	7440-57-5		0.246	mg	1000000	9215				
Bonding wire (Au)	Bonding Wire	0.246	mg	supplier	Metals	Gold	7440-57-5		0.246	mg	1000000	9215				
Leadframe (C7025 + Ni/Pd/Au-Ag)	Copper & its alloys	11.880	mg	supplier	Metals	Copper	7440-50-8		11.478	mg	966120	430052				
				supplier	Metals	Nickel	7440-02-0		0.353	mg	29750	13243				
				supplier	Metals	Silicon	7440-21-3		0.031	mg	2600	1157				
				supplier	Metals	Magnesium	7439-95-4		0.014	mg	1150	512				
				supplier	Metals	Silver	7440-22-4		0.001	mg	80	36				
				supplier	Metals	Gold	7440-57-5		0.001	mg	100	45				
				supplier	Metals	Palladium	7440-05-3		0.002	mg	200	89				